

MM3Z2V4C-MM3Z75VC

Zener Diodes

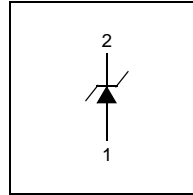
Features

- Wide Zener Voltage Range Selection, 2.4V to 75V
- VZ Tolerance Selection of $\pm 5\%$ (C Series)
- Very Small and Thin SMD package
- Clip Bonding Construction, Good Thermal Capability
- Matte Tin(Sn) finish, Pb Free



SOD-323F

Connection Diagram



Absolute Maximum Ratings T_a = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
P _D	Power Dissipation	200	mW
T _{STG}	Storage Temperature Range	-65 to +150	°C
T _J	Maximum Junction Temperature	150	°C
I _{ZM}	Maximum Regulator Current	P _D /V _Z	mA

* These ratings are limiting values above which the serviceability of the diode may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Unit
R _{θJA}	Thermal Resistance, Junction to Ambient	595	°C/W

* Device mounted on PCB with minimum land pad.

Electrical Characteristics T_{amb} = 25°C unless otherwise specified

Symbol	Parameter/ Test condition	Min.	Typ.	Max.	Unit
V _F	Forward Voltage / I _F =10 mA	--	--	1.0	V

Package Marking and Ordering Information

Device Marking	Device	Package	Packing	Reel Size	Tape Width	Quantity
Refer to Product table list	Refer to Product table list	SOD-323F	Tape & Reel	7'	12mm	3,000

Electrical Characteristics T_A=25°C unless otherwise noted

Device Type	Device Marking	V _Z (V) @ I _{ZT}			Z _{ZT} (Ω) @ I _{ZT}	I _{ZT} (mA)	Z _{ZK} (Ω) @ I _{ZK}	I _{ZK} (mA)	I _R (μA) @ V _R	V _R (V)
		Min.	Typ.	Max.	Max.	-	Max.	-	Max	-
MM3Z2V4C	Z0	2.28	2.4	2.52	94	5	564	1	45	1
MM3Z2V7C	Z1	2.57	2.7	2.84	94	5	564	1	18	1
MM3Z3V0C	Z2	2.85	3	3.15	89	5	564	1	9	1
MM3Z3V3C	Z3	3.14	3.3	3.47	89	5	564	1	4.5	1
MM3Z3V6C	Z4	3.42	3.6	3.78	84	5	564	1	4.5	1
MM3Z3V9C	Z5	3.71	3.9	4.1	84	5	564	1	2.7	1
MM3Z4V3C	Z6	4.09	4.3	4.52	84	5	564	1	2.7	1
MM3Z4V7C	Z7	4.47	4.7	4.94	75	5	470	1	2.7	2
MM3Z5V1C	Z8	4.85	5.1	5.36	56	5	451	1	1.8	2
MM3Z5V6C	Z9	5.32	5.6	5.88	37	5	376	1	0.9	2
MM3Z6V2C	ZA	5.89	6.2	6.51	9	5	141	1	2.7	4
MM3Z6V8C	ZB	6.46	6.8	7.14	14	5	75	1	1.8	4
MM3Z7V5C	ZC	7.11	7.5	7.86	14	5	75	1	0.9	5
MM3Z8V2C	ZD	7.79	8.2	8.61	14	5	75	1	0.63	5
MM3Z9V1C	ZE	8.65	9.1	9.56	14	5	94	1	0.45	6
MM3Z10VC	ZF	9.5	10	10.5	18	5	141	1	0.18	7
MM3Z11VC	ZG	10.45	11	11.55	18	5	141	1	0.09	8
MM3Z12VC	ZH	11.4	12	12.6	23	5	141	1	0.09	8
MM3Z13VC	ZJ	12.35	13	13.65	28	5	160	1	0.09	8
MM3Z15VC	ZK	14.25	15	15.75	28	5	188	1	0.045	10.5
MM3Z16VC	ZL	15.2	16	16.8	37	5	188	1	0.045	11.2
MM3Z18VC	ZM	17.1	18	18.9	42	5	212	1	0.045	12.6
MM3Z20VC	ZN	19	20	21	51	5	212	1	0.045	14
MM3Z22VC	ZP	20.9	22	23.1	51	5	235	1	0.045	15.4
MM3Z24VC	ZR	22.8	24	25.2	65	5	235	1	0.045	16.8
MM3Z27VC	ZS	25.65	27	28.35	75	5	282	0.5	0.045	18.9
MM3Z30VC	ZT	28.5	30	31.5	75	5	282	0.5	0.045	21
MM3Z33VC	ZU	31.35	33	34.65	75	5	306	0.5	0.045	23
MM3Z36VC	ZV	34.2	36	37.8	84	5	329	0.5	0.045	25.2
MM3Z39VC	ZW	37.05	39	40.95	122	5	329	0.5	0.045	27.3
MM3Z43VC	ZX	40.85	43	45.15	141	5	353	0.5	0.045	30.1
MM3Z47VC	ZY	44.65	47	49.35	160	5	353	0.5	0.045	33
MM3Z51VC	Z-	48.45	51	53.55	169	5	376	0.5	0.045	35.7
MM3Z56VC	Z=	53.2	56	58.8	188	5	400	0.5	0.045	39.2
MM3Z62VC	Z≡	58.9	62	65.1	202	5	423	0.5	0.045	43.4
MM3Z68VC	Z>	64.6	68	71.4	226	5	447	0.5	0.045	47.6
MM3Z75VC	Z<	71.25	75	78.75	240	5	470	0.5	0.045	52.5

Notes :

- The Zener Voltage (V_Z) is tested under pulse condition of 10mS.
- The device numbers listed have a standard tolerance on the nominal zener voltage of ±5%.
- The zener impedance is derived from the 60-cycle ac voltage, which results when an ac current having an rms value equal to 10% of the dc zener current (I_{ZT} or I_{ZK}) is superimposed to I_{ZT} or I_{ZK}.

Typical Performance Characteristics

Figure 1. Zener current vs. Zener Voltage

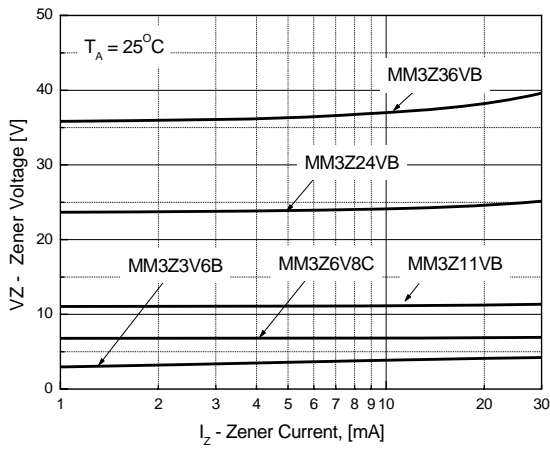


Figure 2. Zener current vs. Zener Impedance

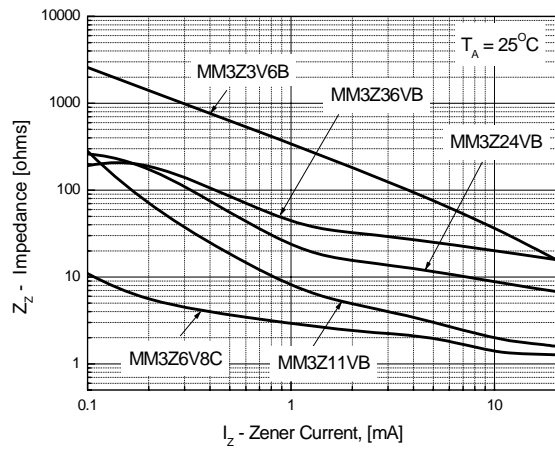


Figure 3. MM3Z3V6B
Zener current vs. Zener Voltage

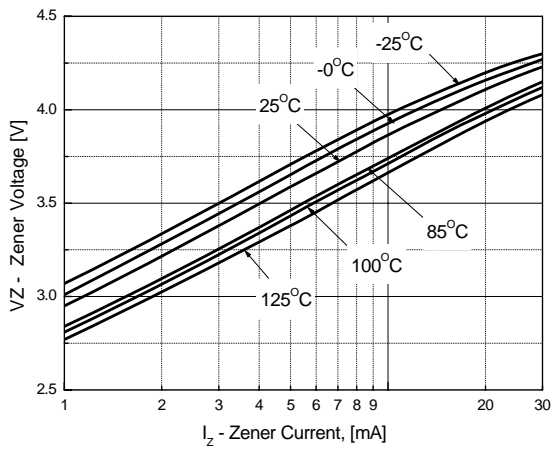


Figure 4. MM3Z6V8C
Zener current vs. Zener Voltage

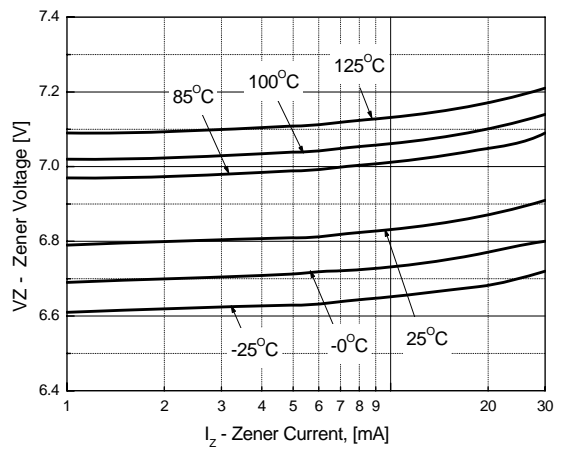


Figure 5. MM3Z11VB
Zener current vs. Zener Voltage

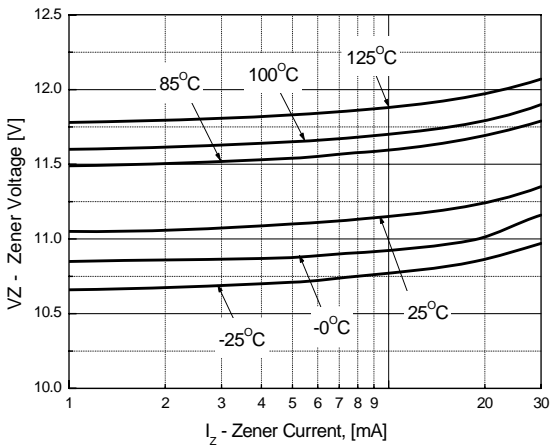
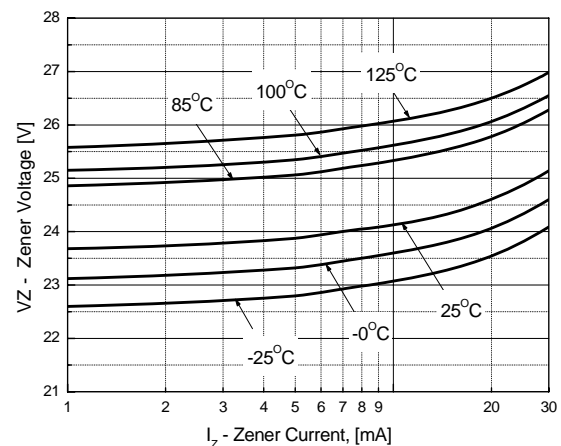
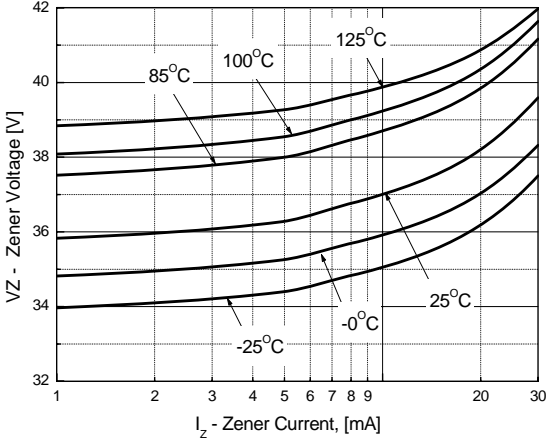


Figure 6. MM3Z24VB
Zener current vs. Zener Voltage



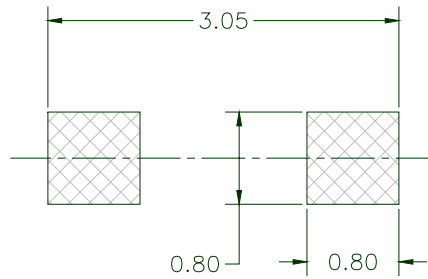
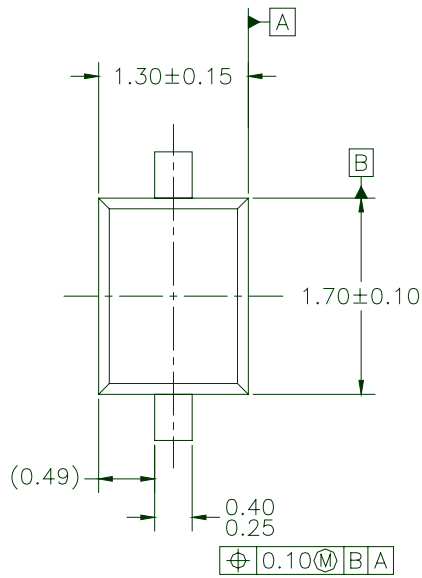
Typical Performance Characteristics

Figure 7. MM3Z36VB
Zener current vs. Zener Voltage

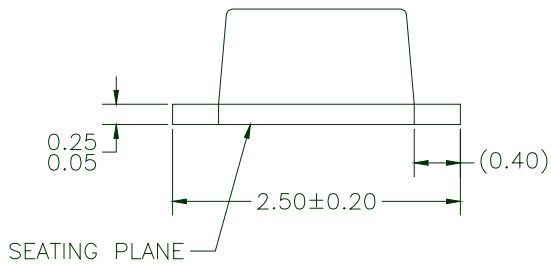


Package Dimensions

SOD - 323F



LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE IS COMPLIANT TO JEITA SC90 STANDARD EXCEPT FOR THE OVERALL PACKAGE HEIGHT.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 1994.



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